



Material Content Data Sheet



Sales Product Name		BTS611L1 E3128A		Issued		1. August 2018		
MA#		MA001124332						
Package		PG-TO263-7-2		Weight*		1507.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.579	0.30	0.30	3037	3037
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		160	
	non noble metal	iron	7439-89-6	0.803	0.05		532	
	non noble metal	copper	7440-50-8	801.714	53.17	53.24	531739	532431
	non noble metal	aluminium	7429-90-5	1.785	0.12	0.12	1184	1184
wire	non noble metal	aluminium	7429-90-5	1.785	0.12	0.12	1184	1184
encapsulation	organic material	carbon black	1333-86-4	6.335	0.42		4202	
	inorganic material	antimonytrioxide	1309-64-4	13.246	0.88		8785	
	plastics	brominated resin	-	14.974	0.99		9931	
	plastics	epoxy resin	-	109.424	7.26		72576	
	inorganic material	silicondioxide	60676-86-0	431.937	28.65	38.20	286483	381977
leadfinish	non noble metal	tin	7440-31-5	12.317	0.82	0.82	8169	8169
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	179	180
solder	non noble metal	tin	7440-31-5	0.075	0.00		50	
	noble metal	silver	7440-22-4	0.094	0.01		62	
	non noble metal	lead	7439-92-1	3.579	0.24	0.25	2374	2486
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		71	
	non noble metal	copper	7440-50-8	106.210	7.04	7.05	70444	70536
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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